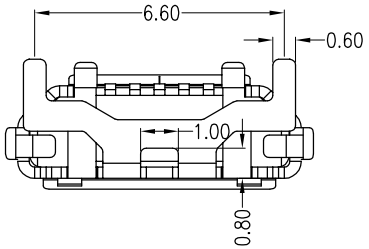
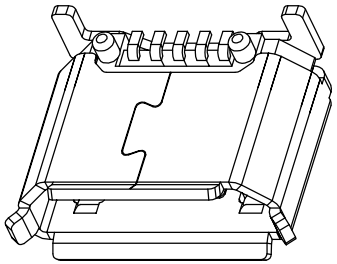
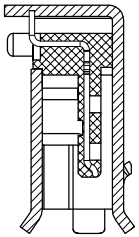
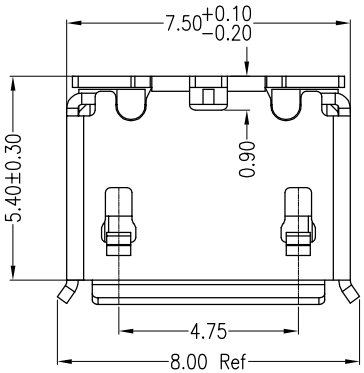
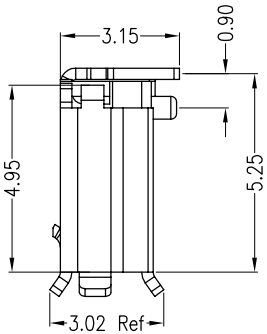
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

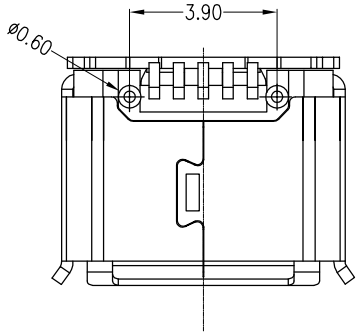


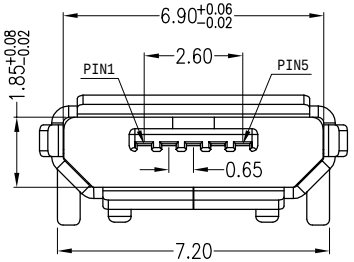


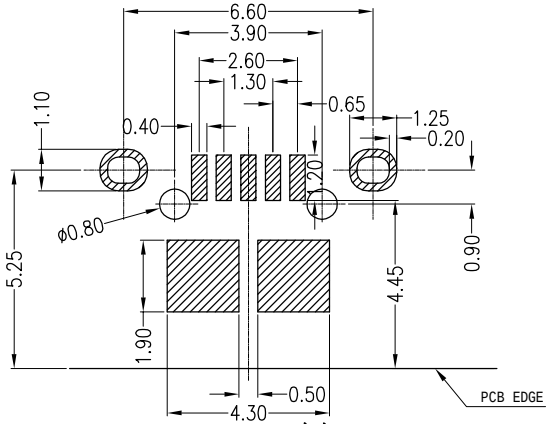












PCB图仅做参考

RECOMMAND PCB LAYOUT

Note:

1.Material:

1.1 Housing: LCP High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.15mm

1.3 Shell: SUS304,t=0.30mm

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: -30°C~80°C

外壳材质

7:SUS304R-1/2H

外壳电镀

1:N50u''

2:雾T50u''

3:N+Au1u''(脚)

4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''
05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''

主体颜色 B:黑色

主体材质 1:LCP

端子材质 4:C5191R-EH

PART NO: USB-F06505-SC053		MATERAL: SEE NOTE	WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD
MODEL NO: XX		FINSH: SEE NOTE	
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	TITLE: MICRO USB 5S B TYPE牛角型6.60/7.2有柱(无前插脚)新模
TOLERANCE UNSPECIFIED .x 0.15 .xx 0.10 .xxx 0.05 Ang. 1°		DR: LIU MIAO	DWG NO: A190 REV: A
		CHK: SIMON	
		APP: DAVID	SCALE: 4:1 DATE: 2012.07.13